

HAT1096C

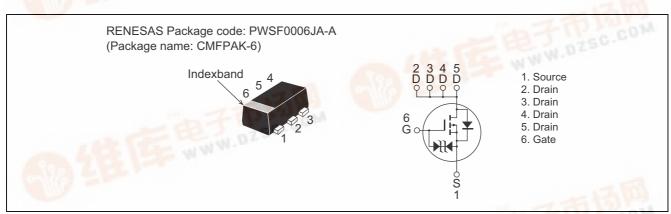
Silicon P Channel MOS FET Power Switching

REJ03G1233-0400 Rev.4.00 Jan 26, 2006

Features

- Low on-resistance $R_{DS(on)} = 225 \text{ m}\Omega \text{ typ. (at } V_{GS} = -4.5 \text{ V})$
- Low drive current.
- 2.5 V gate drive devices.
- High density mounting

Outline



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Ratings	Unit
Drain to Source voltage	V _{DSS}	-20	V
Gate to Source voltage	V _{GSS}	±12	V
Drain current	I _D	-1	А
Drain peak current	I _D (pulse) ^{Note1}	-4	A
Body - Drain diode reverse drain current	I _{DR}	-1	Α
Channel dissipation	Pch ^{Note 2}	790	mW
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes: 1. PW \leq 10 μ s, duty cycle \leq 1%

2. When using the glass epoxy board. (FR4 $40 \times 40 \times 1.6$ mm), Ta = 25°C



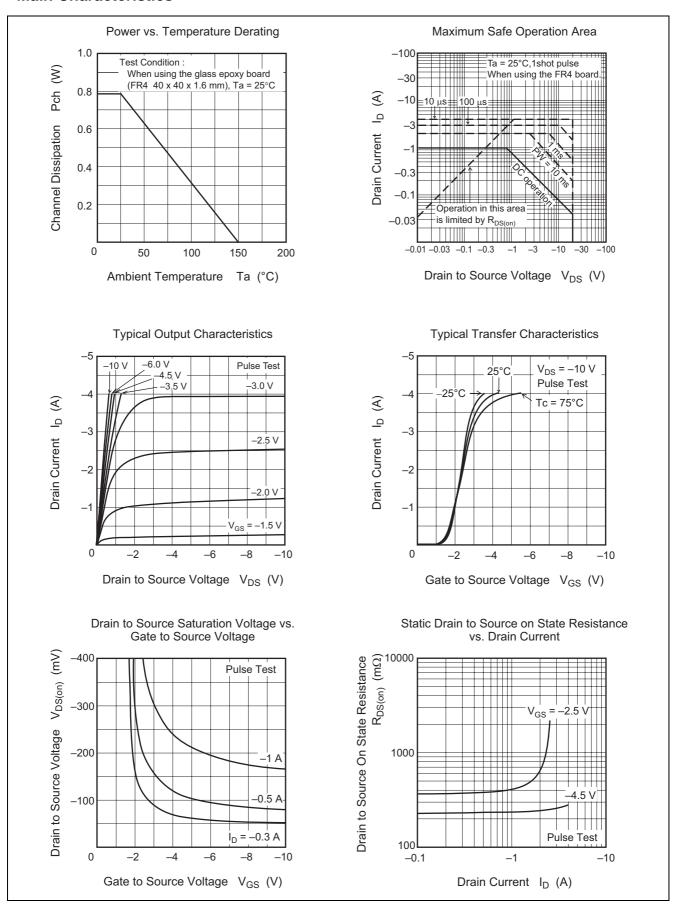
Electrical Characteristics

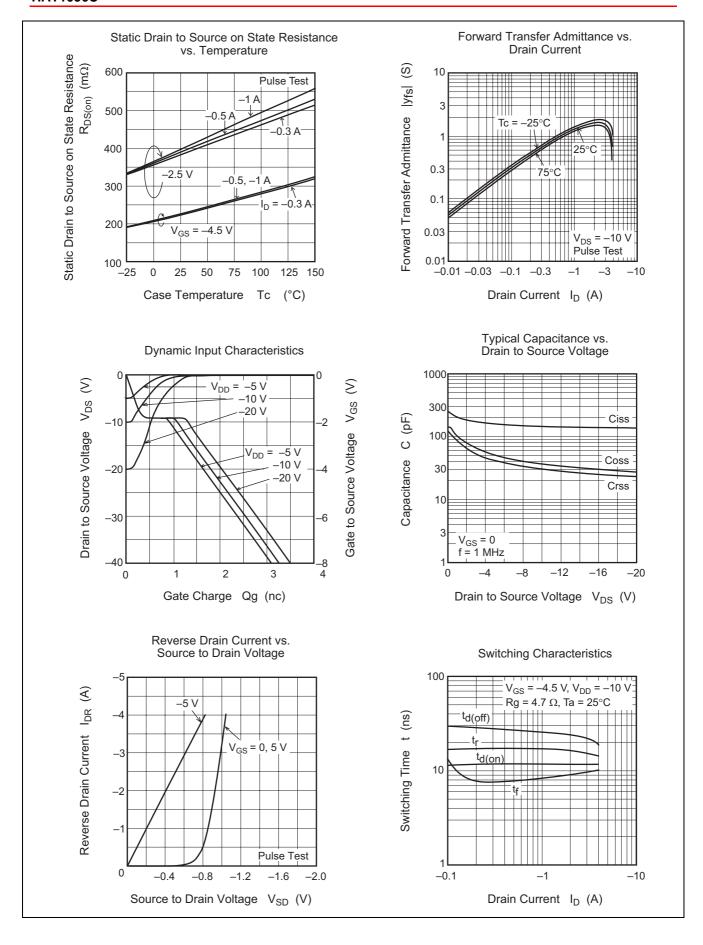
 $(Ta = 25^{\circ}C)$

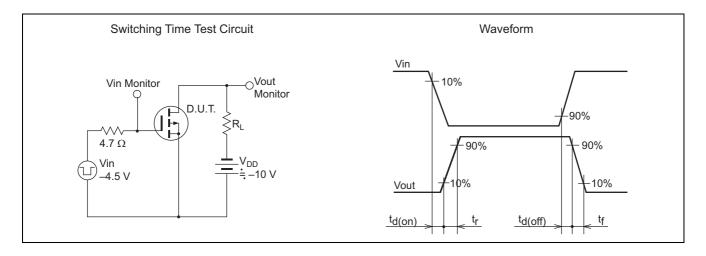
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to Source breakdown	$V_{(BR)DSS}$	-20	_	_	V	$I_D = -10 \text{ mA}, V_{GS} = 0$
voltage						
Gate to Source breakdown voltage	$V_{(BR)GSS}$	±12	_		V	$I_G = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to Source leakage current	I_{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 10 \text{ V}, V_{DS} = 0$
Drain to Source leakage current	I _{DSS}	_	_	-1	μΑ	$V_{DS} = -20 \text{ V}, V_{GS} = 0$
Gate to Source cutoff voltage	$V_{GS(th)}$	-0.4	_	-1.4	V	$I_D = -1 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Drain to Source on state	R _{DS(on)}	_	225	293	mΩ	$I_D = -0.5 \text{ mA}, V_{GS} = -4.5 \text{ V}^{\text{Note3}}$
resistance		_	380	530	mΩ	$I_D = -0.5 \text{ mA}, V_{GS} = -2.5 \text{ V}^{\text{Note3}}$
Forward transfer admittance	y _{fs}	0.6	0.9	_	S	$I_D = -0.5 \text{ mA}, V_{DS} = -10 \text{ V}^{\text{Note3}}$
Input capacitance	Ciss	_	155	_	pF	$V_{DS} = -10 \text{ V}, V_{GS} = 0,$
Output capacitance	Coss	_	40	_	pF	f = 1 MHz
Reverse transfer capacitance	Crss	_	30	_	pF	
Total gate charge	Qg	_	2	_	nC	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V},$
Gate to Source charge	Qgs	_	0.4	_	nC	I _D = -1 A
Gate to Drain charge	Qgd	_	0.6	_	nC	
Turn - on delay time	t _{d(on)}	_	12	_	ns	$V_{DS} = -10 \text{ V}, \ V_{GS} = -4.5 \text{ V},$ $I_{D} = -0.5 \text{ A}, \ R_{L} = 20 \ \Omega,$ $R_{g} = 4.7 \ \Omega$
Rise time	t _r	_	18	_	ns	
Turn - off delay time	t _{d(off)}	_	28	_	ns	
Fall time	t _f	_	8	_	ns	
Body - Drain diode forward voltage	V_{DF}		-0.85	-1.1	V	$I_F = -1 A, V_{GS} = 0$

Notes: 3. Pulse test

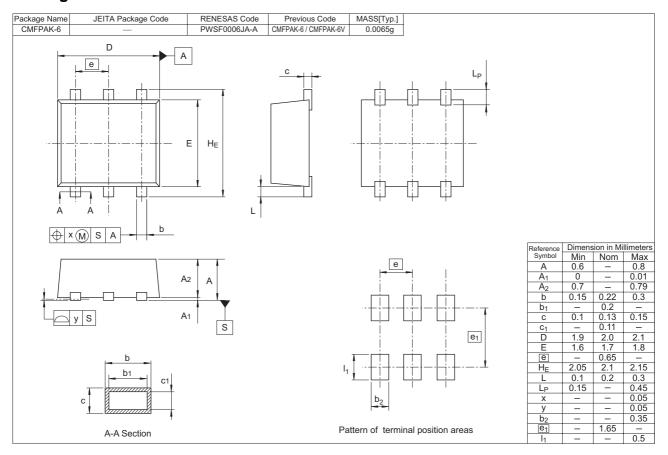
Main Characteristics







Package Dimensions



Ordering Information

Part Name	Quantity	Shipping Container
HAT1096C-EL-E	3000 pcs	Taping

Note: For some grades, production may be terminated. Please contact the Renesas sales office to check the state of production before ordering the product.

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